PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent No.:	US 7,345,365 B2	Issue Date:	03/18/2008
Serial No.:	10/728,150	Filing Date:	12/03/2003
Inventor:	Jin-Yuan Lee et al.		
Docket No.:	MEGP0012USA1		

Title: ELECTRONIC COMPONENT WITH DIE AND PASSIVE DEVICE

To: Commissioner for Patents
P.O. BOX 1450
Alexandria, VA 22313-1450

Subject: Request for Certificate of Correction of Office Mistake

Dear Sir:

The above-identified patent was issued on 03/18/2008. The applicants found that the Related U.S. Application Data and Foreign Application Priority Data were missed on the front page of the patent (Attachment 1). Documents on record indicate this as an Office mistake of consequence.

The patent is a divisional application of, and claims the priority benefit of, U.S. application serial No. 10/055,499 filed on 01/22/2002. The Related U.S. Application Data listed on the specification submitted on 12/03/2003 (Attachment 2) and the Office Action of 07/06/2004 pointed out the PTO had received the priority documents. (Attachment 3, PTOL-326, page 2)

The applicants submitted priority document and claimed for foreign priority on 12/03/2003. Both of the declaration (Attachment 4) and the specification (Attachment 5) submitted on 12/03/2003 indicate that the PTO received the submission of priority

document and claimed for foreign priority on 12/03/2003.

The applicants hereby request that a Certificate of Correction be issued under 37 CFR 1.322 **to supplement the Related U.S. Application Data (Division of application No. 10/055,499, filed on 01/22/2002) and the Foreign Application Priority Data (Taiwan patent application No. 90133093 dated 12/31/2001).**

Sincerely yours,

/Winston Hsu/ Date: 02/26/2009

Winston Hsu, Patent Agent No. 41,526
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Note: Please leave a message in my voice mail if you need to talk to me. (The time in D.C. is 13 hours behind the Taiwan time, i.e. 9 AM in D.C. = 10 PM in Taiwan.)

PTO/SB/44 (09-07)
Approved for use through 08/31/2010. OMB 0651-0033
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

(Also Form PTO-1050)

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7345365

APPLICATION NO.: 10/728,150

ISSUE DATE : 3/18/2008

INVENTOR(S) : Jin-Yuan Lee et al.

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On Title Page

Under item (65), Insert item (62) "Related U.S. Application Data," and add--Division of application No. 10/055,499, filed on Jan. 22, 2002.--

Under item (62), Insert item (30) "Foreign Application Priority Data," and add--Dec. 31, 2001 (TW) ----------90133093 A--

MAILING ADDRESS OF SENDER (Please do not use customer number below):

Attachment 1

US007345365B2

(12) **United States Patent**
Lee et al.

(10) **Patent No.: US 7,345,365 B2**
(45) **Date of Patent: Mar. 18, 2008**

(54) **ELECTRONIC COMPONENT WITH DIE AND PASSIVE DEVICE**

Please supply the Related U.S. Application Data (Division of application No. 10/055,499, filed on 01/22/2002)

(75) Inventors: **Jin-Yuan Lee**, Hsinchu (TW); **Mou-Shiung Lin**, Hsinchu (TW); **Ching-Cheng Huang**, Hsinchu (TW)

(73) Assignee: **MEGICA Corporation**, Hsinchu (TW)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

(21) Appl. No.: **10/728,150**

(22) Filed: **Dec. 3, 2003**

(65) **Prior Publication Data**

US 2004/0119097 A1 Jun. 24, 2004

(51) **Int. Cl.**

H01L 23/52	(2006.01)
H01L 23/48	(2006.01)
H01L 23/40	(2006.01)
H01L 23/34	(2006.01)
H01L 23/538	(2006.01)

Please supply the Foreign Application Priority Data (Taiwan patent application No. 90133093 dated 12/31/2001)

(52) **U.S. Cl.** **257/724**; 257/723; 257/774; 257/E23.174; 257/E23.177

(58) **Field of Classification Search** 257/723–724, 257/700, 774, 781, 698, E23.174, E23.177
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

4,402,888	A *	9/1983	Runck	264/448
5,049,980	A *	9/1991	Saito et al.	257/758
5,874,770	A *	2/1999	Saia et al.	257/536
6,025,995	A *	2/2000	Marcinkiewicz	361/760
6,121,688	A	9/2000	Akagawa	257/778
6,159,767	A *	12/2000	Eichelberger	438/107
6,205,032	B1 *	3/2001	Shepherd	361/793
6,274,391	B1 *	8/2001	Wachtler et al.	438/6
6,396,148	B1 *	5/2002	Eichelberger et al.	257/758
6,486,535	B2 *	11/2002	Liu	257/666
6,603,072	B1 *	8/2003	Foster et al.	174/52.4
6,614,110	B1 *	9/2003	Pace	257/737
6,620,513	B2 *	9/2003	Yuyama et al.	428/416

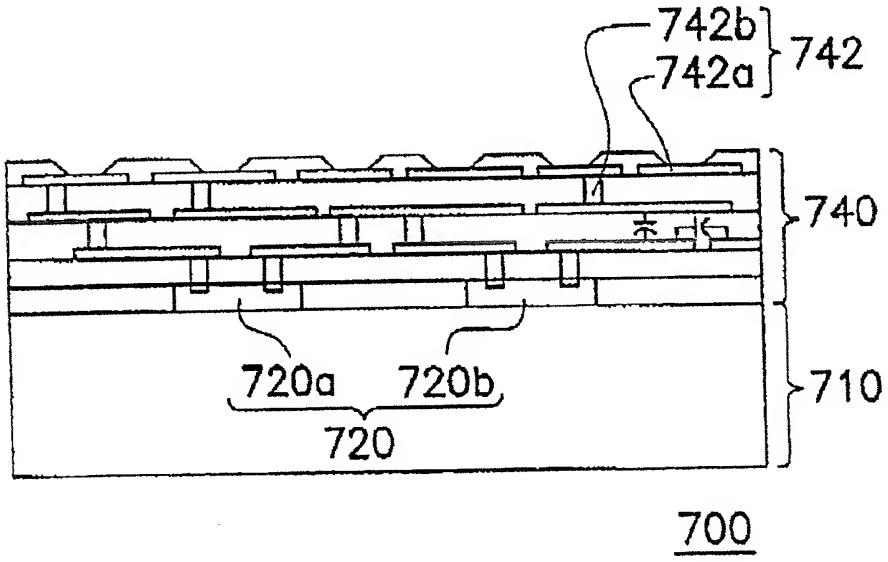
* cited by examiner

Primary Examiner—Luan Thai
(74) *Attorney, Agent, or Firm*—Winston Hsu

(57) **ABSTRACT**

An integrated chip package structure and method of manufacturing the same is by adhering dies on an organic substrate and forming a thin-film circuit layer on top of the dies and the organic substrate. Wherein the thin-film circuit layer has an external circuitry, which is electrically connected to the metal pads of the dies, that extends to a region outside the active surface of the dies for fanning out the metal pads of the dies. Furthermore, a plurality of active devices and an internal circuitry is located on the active surface of the dies. Signal for the active devices are transmitted through the internal circuitry to the external circuitry and from the external circuitry through the internal circuitry back to other active devices. Moreover, the chip package structure allows multiple dies with different functions to be packaged into an integrated package and electrically connecting the dies by the external circuitry.

34 Claims, 17 Drawing Sheets



Attachment 2

In The Specification:

Paragraph beginning at line 7 of page 1 has been amended as follows:

~~This application claims the priority benefit of Taiwan application serial no. 90133093, filed December 31, 2001.~~This application is a divisional application of, and claims the priority benefit of, U.S. application serial No. 10/055,499 filed on January 22, 2002.

Attachment 3

Office Action Summary	Application No.	Applicant(s)	
	10/728,150	LEE ET AL.	
	Examin r	Art Unit	
	Luan Thai	2827	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 1 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1)☐ Responsive to communication(s) filed on _____.

2a)☐ This action is **FINAL**. 2b)☐ This action is non-final.

3)☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4)☒ Claim(s) *1-60 and 176-203* is/are pending in the application.

4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5)☐ Claim(s) _____ is/are allowed.

6)☐ Claim(s) _____ is/are rejected.

7)☐ Claim(s) _____ is/are objected to.

8)☒ Claim(s) *1-60 and 176-203* are subject to restriction and/or election requirement.

Application Papers

9)☐ The specification is objected to by the Examiner.

10)☐ The drawing(s) filed on _____ is/are: a)☐ accepted or b)☐ objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11)☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12)☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a)☒ All b)☐ Some * c)☐ None of:

1.☐ Certified copies of the priority documents have been received.

2.☒ Certified copies of the priority documents have been received in Application No. 10/055,499.

3.☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) ☐ Notice of References Cited (PTO-892)
2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date _____.
4) ☐ Interview Summary (PTO-413) Paper No(s)/Mail Date. _____.
5) ☐ Notice of Informal Patent Application (PTO-152)
6) ☐ Other: _____.

Attachment 4

P534

COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:
My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

INTEGRATED CHIP PACKAGE STRUCTURE USING ORGANIC SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

the specification of which

_X_ is attached hereto.
___ was filed on _____
as Application Serial No._____ and was amended on_____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:
Prior Foreign Application(s):

Number	Country	Date Filed(yyyy/mm/dd)	Yes	No
90133093	Taiwan, R.O.C.	2001/12/31	X	

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Jiawei Huang	(Reg. No. 43,330)	Charles C.H. Wu	(Reg. No. 39,081)
Maria Erlinda C. Sarno	(Reg. No. 37,436)	Chanette Armstrong	(Reg. No. 44,011)
Belinda Lee	(Reg. No. 46,863)		

SEND CORRESPONDENCE TO:

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DIRECT TELEPHONE CALLS TO:
(Name and telephone number)

Jiawei Huang
(949) 660-0762

Attachment 5

8534USF.RTF

INTEGRATED CHIP PACKAGE STRUCTURE USING ORGANIC SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

CROSS-REFERENCE TO RELATED APPLICATION

This application claims the priority benefit of Taiwan application serial no. 90133093, filed December 31, 2001.

BACKGROUND OF THE INVENTION

Field of the invention:

[0001] The present invention relates to an integrated chip package structure and method of manufacture the same. More particularly, the present invention relates to an integrated chip package structure and method of manufacture the same using organic substrate.

Description of related art

[0002] In the recent years, the development of advanced technology is on the cutting edge. As a result, high-technology electronics manufacturing industries launch